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## **Patent Assignment Abstract of Title**

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**Total Assignments: 1** 

Patent #: <u>5851845</u> Issue Dt: 12/22/1998 Application #: 08574403 Filing Dt: 12/18/1995

Inventors: ALAN G. WOOD, WARREN M. FARNWORTH

Title: PROCESS FOR PACKING A SEMICONDUCTOR DIE USING AND TESTING

Assignment: 1

Conveyance: ASSIGNMENT OF ASSIGNORS INTEREST (SEE DOCUMENT FOR DETAILS).

Assignors: FARNWORTH, WARREN M.

**Exec Dt:** 12/12/1995

WOOD, ALAN G. **Exec Dt:** 12/12/1995

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